

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2666153

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>FEN CHEN</td> <td>12/02/2013</td> </tr> <tr> <td>MUKTA G. FAROOQ</td> <td>11/26/2013</td> </tr> <tr> <td>JEFFREY P. GAMBINO</td> <td>11/25/2013</td> </tr> <tr> <td>ZHONG-XIANG HE</td> <td>11/26/2013</td> </tr> <tr> <td>KEVIN S. PETRARCA</td> <td>11/25/2013</td> </tr> <tr> <td>ANTHONY K. STAMPER</td> <td>12/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	FEN CHEN	12/02/2013	MUKTA G. FAROOQ	11/26/2013	JEFFREY P. GAMBINO	11/25/2013	ZHONG-XIANG HE	11/26/2013	KEVIN S. PETRARCA	11/25/2013	ANTHONY K. STAMPER	12/02/2013
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RECEIVING PARTY DATA															
Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION														
Street Address:	NEW ORCHARD ROAD														
City:	ARMONK														
State/Country:	NEW YORK														
Postal Code:	10504														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14146788</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14146788										
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Application Number:	14146788														
CORRESPONDENCE DATA															
Fax Number:	(410)630-1656														
Phone:	4107056400														
Email:	mccoy@gibbiplaw.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	GIBB & RILEY, LLC														
Address Line 1:	844 WEST STREET														
Address Line 2:	SUITE 100														
Address Line 4:	ANNAPOLIS, MARYLAND 21401														
NAME OF SUBMITTER:	PAMELA M. RILEY, ESQ.														

Signature:	/Pamela M. Riley/
Date:	01/03/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 12 source=BUR920130161US1_Assignment-Declaration#page1.tif source=BUR920130161US1_Assignment-Declaration#page2.tif source=BUR920130161US1_Assignment-Declaration#page3.tif source=BUR920130161US1_Assignment-Declaration#page4.tif source=BUR920130161US1_Assignment-Declaration#page5.tif source=BUR920130161US1_Assignment-Declaration#page6.tif source=BUR920130161US1_Assignment-Declaration#page7.tif source=BUR920130161US1_Assignment-Declaration#page8.tif source=BUR920130161US1_Assignment-Declaration#page9.tif source=BUR920130161US1_Assignment-Declaration#page10.tif source=BUR920130161US1_Assignment-Declaration#page11.tif source=BUR920130161US1_Assignment-Declaration#page12.tif	

DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT

Title of Invention: SEMICONDUCTOR CHIP WITH A DUAL DAMASCENE WIRE AND THROUGH-SUBSTRATE VIA (TSV) STRUCTURE

As a below named and undersigned inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

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I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

Whereas, I ("ASSIGNOR") have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document;

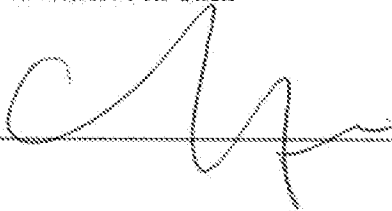
Whereas, International Business Machines Corporation (herein referred to as the "ASSIGNEE"), a corporation of New York having a place of business at Armonk, New York, desires to acquire, and I desire to grant to the ASSIGNEE, my entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, I hereby sell or have sold, assign or have assigned, and otherwise transfer or have transferred to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefore in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by me had this Assignment not been made; and I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in the ASSIGNEE, its successors, legal representatives, and assigns, whenever requested by the ASSIGNEE, its successors, legal representatives, or assigns.

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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: Fen Chen

Signature:  Date: 12/2/2013

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(2) Legal Name of Inventor: Mukta G. Farooq

Signature: Mukta G. Farooq Date: Nov. 26, 2013

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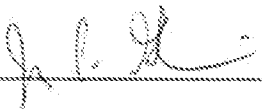
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(3) Legal Name of Inventor: Jeffrey P. Gambino

Signature:  Date: Nov 25, 2017

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(4) Legal Name of Inventor: Zhong-Xiang He

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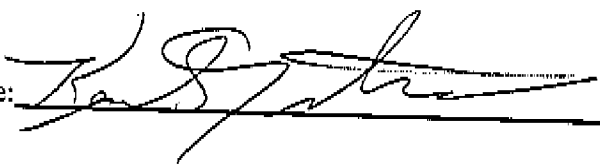
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(5) Legal Name of Inventor: Kevin S. Petrarca

Signature:  Date: 11/25/13

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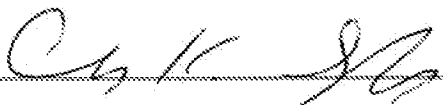
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(6) Legal Name of Inventor: Anthony K. Stamper

Signature:  Date: 12/2/2013